

	Type	L #	Hits	Search Text	DBs	Time Stamp	Com men ts	Er ror De fini tion	Er ror s
1	BRS	L13	301325	polishing or cmp or slurry	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/14 11:23			0
2	BRS	L19	29230	azole or triazole	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/14 09:02			0
3	BRS	L25	2871	13 and 19	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/14 09:03			0
4	BRS	L31	164593	(H adj "2" adj O adj "2") or H2O2 or peroxide	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/14 09:07			0
5	BRS	L37	315665	\$5phosphate or phosphonic or phosphono	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/14 09:15			0
6	BRS	L43	922	25 and 31	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/14 09:15			0
7	BRS	L49	664	43 and 37	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/14 09:16			0
8	BRS	L61	116187	438/\$.ccls.	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/14 14:13			0
9	BRS	L67	15326	216/\$.ccls.	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/14 09:17			0
10	BRS	L79	24604	510/\$.ccls.	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/14 09:17			0

	Type	L #	Hits	Search Text	DBs	Time Stamp	Com men ts	Er ror De fin iti on	Er ror s
11	BRS	L91	3579	67 and 61	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/14 09:18			0
12	BRS	L103	80378	252/\$.ccls.	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/14 14:29			0
13	BRS	L115	44	55 and 79	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/14 09:20			0
14	BRS	L85	1	55 and 61	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/14 09:20			0
15	BRS	L109	2	55 and 67	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/14 09:29			0
16	BRS	L121	29	55 and 103	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/14 09:30			0
17	BRS	L55	474	49 and @pd<=19990810	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/14 09:33			0
18	BRS	L127	396	13 and (nonaqueous adj solvent)	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/14 11:16			0
19	BRS	L138	1	(13 and (nonaqueous adj solvent)) same (Cu or Ta)	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/14 11:21			0
20	BRS	L144	396	13 and (nonaqueous adj solvent)	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/14 11:21			0

	Type	L #	Hits	Search Text	DBs	Time Stamp	Com men ts	Er ror De fin iti on	Er ror s
21	BRS	L150	0	(13 and (nonaqueous adj solvent)) same (Cu or Ta) same ("no abrasive")	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/14 11:23			0
22	BRS	L156	117	(polishing or cmp or slurry) same "no abrasive"	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/14 13:29			0
23	BRS	L162	0	"aminiethylethanolamine or polyethyleneimine" and 13	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/14 13:30			0
24	BRS	L168	0	"aminoethylethanolamine or polyethyleneimine" and 13	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/14 13:31			0
25	BRS	L174	0	"aminoethylethanolamine or polyethyleneimine" and ("chemical mecahnical polishing" or cmp or slurry or polish\$3)	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/14 13:31			0
26	BRS	L180	0	"aminoethylethanolamine or polyethyleneimine" and ("chemical mechanical polishing" or cmp or slurry or polish\$3)	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/14 13:32			0
27	BRS	L186	0	"aminoethylethanolamine or polyethyleneimine"	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/14 13:32			0
28	BRS	L192	1274	("aminoethylethanolamine" or "polyethyleneimine") and (cmp or "chemical mechanical polishing" or slurry or polish\$3)	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/14 13:34			0
29	BRS	L198	156	("aminoethylethanolamine" or "polyethyleneimine") and (cmp or "chemical mechanical polishing" or slurry or polish\$3) same (Cu or Ta or metal or semiconductor)	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/14 14:07			0

	Type	L #	Hits	Search Text	DBs	Time Stamp	Com men ts	Er ror De fin iti on	Er ror s
30	BRS	L204	7434	(PVA or "polyvinylalcohol" or "polyethylene oxide" or "polypropylene oxide" or (sulfonate adj3 polymer)) and (cmp or "chemical mechanical polishing" or slurry or polish\$3)	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/14 14:23			0
31	BRS	L210	1210	(PVA or "polyvinylalcohol" or "polyethylene oxide" or "polypropylene oxide" or (sulfonate adj3 polymer)) and (cmp or "chemical mechanical polishing" or slurry or polish\$3) same (Cu or Ta or metal or semiconductor)	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/14 14:12			0
32	BRS	L216	34	438/\$.ccls. and 210	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/14 14:27			0
33	BRS	L222	7434	(PVA or "polyvinylalcohol" or "polyethylene oxide" or (sulfonic adj3 polymer) or "polypropylene oxide" or (sulfonate adj3 polymer)) and (cmp or "chemical mechanical polishing" or slurry or polish\$3)	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/14 14:32			0
34	BRS	L228	1210	(PVA or "polyvinylalcohol" or "polyethylene oxide" or (sulfonic adj3 polymer) or "polypropylene oxide" or (sulfonate adj3 polymer)) and (cmp or "chemical mechanical polishing" or slurry or polish\$3) same (Cu or Ta or metal or semiconductor)	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/14 14:26			0
35	BRS	L234	34	438/\$.ccls. and 228	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/14 15:01			0
36	BRS	L240	4	252/\$.ccls. and 234	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/14 14:29			0

	Type	L #	Hits	Search Text	DBs	Time Stamp	Co m m e n t s	Er r o r D e f i n i t i o n	Er r o r s
37	BRS	L246	7613	(PVA or "polyvinylalcohol" or "polyethylene oxide" or (sulfonic adj3 polymer) or "polypropylene oxide" or (sulfonate adj3 polymer)) and (cmp or "chemical mechanical polishing" or slurry or polish\$3)	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/14 14:33			0
38	BRS	L252	50	438/\$.ccls. and 246	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/14 15:10			0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
1	BRS	540922	amine or (amino adj alcohol) or amide or imine or (imino adj acid) or nitrile or nitro	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/13 16:42			0
2	BRS	51367	thiol or thioester or thioether or carbothiolic or carbothionic or thiocarboxylic or thiosalicylic	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/13 16:40			0
3	BRS	98994	abrasive	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/13 18:07			0
4	BRS	315665	\$5phosphate or phosphonic or phosphono	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/14 09:13			0
5	BRS	17379	(polishing or cmp or slurry) and ((H adj "2" adj O adj "2") or H2O2 or peroxide)	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/13 16:43			0
6	BRS	492	((polishing or cmp or slurry) and ((H adj "2" adj O adj "2") or H2O2 or peroxide) and (\$5phosphate or phosphonic or phosphono) and abrasive) and water	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/13 18:08			0
7	BRS	25	((polishing or cmp or slurry) and ((H adj "2" adj O adj "2") or H2O2 or peroxide) and (\$5phosphate or phosphonic or phosphono) and abrasive) and (nonaqueous)	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/13 18:09			0
8	BRS	492	((polishing or cmp or slurry) and ((H adj "2" adj O adj "2") or H2O2 or peroxide) and (\$5phosphate or phosphonic or phosphono) and abrasive) and water	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/13 16:46			0
9	BRS	337	((polishing or cmp or slurry) and ((H adj "2" adj O adj "2") or H2O2 or peroxide) and (\$5phosphate or phosphonic or phosphono) and abrasive) and water) and @pd<=19990810	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/13 16:48			0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
10	BRS	19	((polishing or cmp or slurry) and ((H adj "2" adj O adj "2") or H2O2 or peroxide) and (\$5phosphate or phosphonic or phosphono) and abrasive) and (nonaqueous)) and @pd<=19990810	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/13 16:47			0
11	BRS	303	((polishing or cmp or slurry) and ((H adj "2" adj O adj "2") or H2O2 or peroxide) and (\$5phosphate or phosphonic or phosphono) and abrasive) and water) and @pd<=19990810 and (semiconductor or metal or substrate)	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/13 17:16			0
12	BRS	19	((polishing or cmp or slurry) and ((H adj "2" adj O adj "2") or H2O2 or peroxide) and (\$5phosphate or phosphonic or phosphono) and abrasive) and (nonaqueous)) and @pd<=19990810 and (semiconductor or metal or substrate)	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/13 17:11			0
13	BRS	28008	heterocyclic near5 nitrogen	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/13 17:39			0
14	BRS	3172	(heterocyclic near5 nitrogen) and (polishing or cmp or slurry)	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/13 17:59			0
15	BRS	26	(polishing or cmp or slurry) and ((H adj "2" adj O adj "2") or H2O2 or peroxide) and (\$5phosphate or phosphonic or phosphono) and abrasive and (heterocyclic near5 nitrogen)	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/13 17:13			0
16	BRS	3034	(heterocyclic near5 nitrogen) and (cmp or "chemical mecahnical polishing" or slurry)	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/13 17:16			0
17	BRS	942	(heterocyclic near5 nitrogen) and (cmp or "chemical mecahnical polishing" or slurry) and ((H adj "2" adj O adj "2") or H2O2 or peroxide)	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/13 17:16			0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
18	BRS	666	((heterocyclic near5 nitrogen) and (cmp or "chemical mecahnical polishing" or slurry) and ((H adj "2" adj O adj "2") or H2O2 or peroxide)) and @pd<=19990810 and (semiconductor or metal or substrate)	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/13 18:09			0
19	BRS	682	((heterocyclic near5 nitrogen) and (polishing or cmp or slurry) and ((H adj "2" adj O adj "2") or H2O2 or peroxide)) and @pd<=19990810 and (semiconductor or metal or substrate)	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/13 17:37			0
20	BRS	19	(((((polishing or cmp or slurry) and ((H adj "2" adj O adj "2") or H2O2 or peroxide) and (\$5phosphate or phosphonic or phosphono) and abrasive) and (nonaqueous)) and @pd<=19990810 and (semiconductor or metal or substrate)) and ((H adj "2" adj O adj "2") or H2O2 or peroxide)	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/13 17:40			0
21	BRS	19	(((((polishing or cmp or slurry) and ((H adj "2" adj O adj "2") or H2O2 or peroxide) and (\$5phosphate or phosphonic or phosphono) and abrasive) and (nonaqueous)) and @pd<=19990810 and (semiconductor or metal or substrate)) and ((H adj "2" adj O adj "2") or H2O2 or peroxide) and (polishing or cmp or slurry)	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/13 17:40			0
22	BRS	980	((heterocyclic near5 nitrogen) and (polishing or cmp or slurry) and ((H adj "2" adj O adj "2") or H2O2 or peroxide)	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/13 17:59			0
23	BRS	0	((heterocyclic near5 nitrogen) and (polishing or cmp or slurry)) and 438/\$.ccls	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/13 18:18			0
24	BRS	106	((heterocyclic near5 nitrogen) and (polishing or cmp or slurry)) and 252/\$.ccls	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/13 18:06			0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
25	BRS	31158	(polishing or cmp or slurry) and amine	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/13 18:07			0
26	BRS	6940	(polishing or cmp or slurry) and amine and ((H adj "2" adj O adj "2") or H2O2 or peroxide)	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/13 18:07			0
27	BRS	402	abrasive and ((polishing or cmp or slurry) and amine and ((H adj "2" adj O adj "2") or H2O2 or peroxide))	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/13 18:08			0
28	BRS	393	(abrasive and ((polishing or cmp or slurry) and amine and ((H adj "2" adj O adj "2") or H2O2 or peroxide))) and water	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/13 18:08			0
29	BRS	23	(abrasive and ((polishing or cmp or slurry) and amine and ((H adj "2" adj O adj "2") or H2O2 or peroxide))) and (nonaqueous)	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/13 18:09			0
30	BRS	245	((abrasive and ((polishing or cmp or slurry) and amine and ((H adj "2" adj O adj "2") or H2O2 or peroxide))) and water) and @pd<=19990810 and (semiconductor or metal or substrate)	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/13 18:17			0
31	BRS	3072	polishing and amine	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/13 18:18			0
32	BRS	142	(polishing and amine) and 438/\$.ccls.	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/12/13 18:19			0